

Trimming Clean using SAPS Megasonic Technology on Xtacking 3D NAND

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Fig. 4: Comparison of six clean mode (Mode1-Mode 6) to surface PA remove ability

Fig.5: SEM image of wafer edge with (a) Mode 2 (FW Mega-45W); (b) Mode 6 (HF+SC1+SC2)

Figure 6:

